

FEATURES

- DUAL PROGRAMMABLE TRANSIENT SUPPRESSOR.
- WIDE NEGATIVE FIRING VOLTAGE RANGE :
 $V_{MGL} = -80V$ max.
- LOW DYNAMIC SWITCHING VOLTAGES :
 V_{FP} and V_{DGL} .
- LOW GATE TRIGGERING CURRENT :
 $I_{GT} = 5mA$ max.
- PEAK PULSE CURRENT :
 $I_{PP} = 30A$ for 10/1000 μs surge.
- HOLDING CURRENT :
 $I_H = 150mA$.

DESCRIPTION

This device has been especially designed to protect subscriber line card interfaces (SLIC) against transient overvoltages.

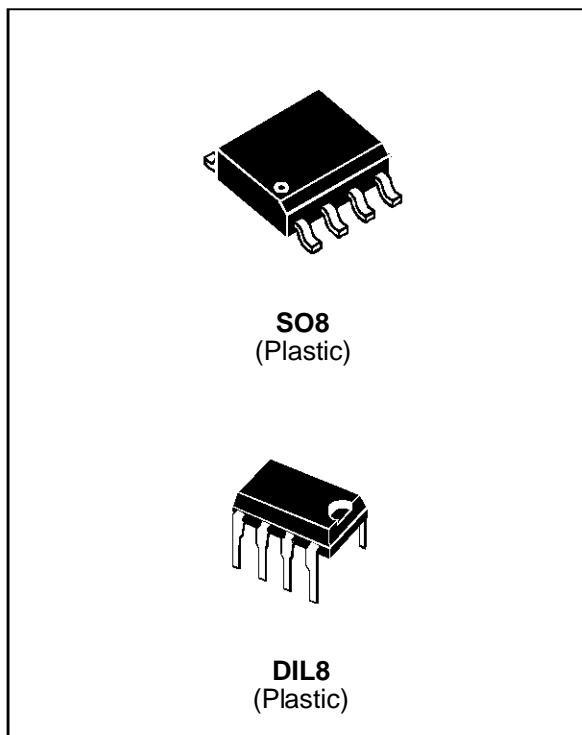
Positive overloads are clipped with 2 diodes. Negative surges are suppressed by 2 thyristors, the breakdown voltage of which is referenced to $-V_{BAT}$ through the gate.

This component presents a very low gate triggering current (I_{GT}) in order to reduce the current consumption on printed circuit board during the firing phase.

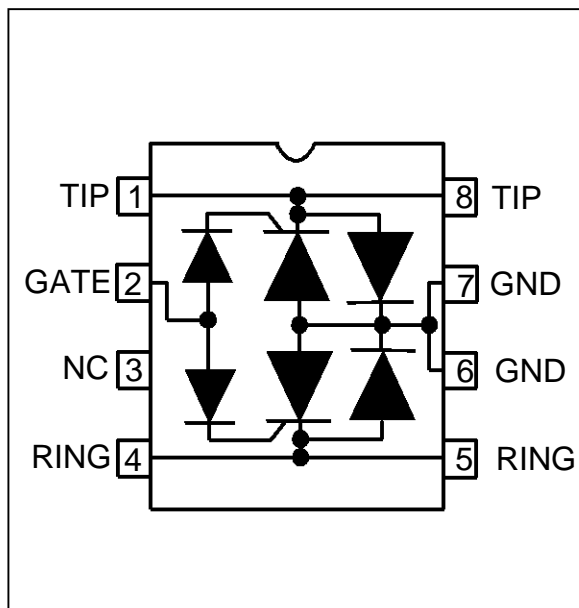
A particular attention has been given to the internal wire bonding. A "4-point" configuration ensures a reliable protection, eliminating the overvoltage introduced by the parasitic inductances of the wiring ($L di/dt$), especially for very fast transients.

COMPLIES WITH FOLLOWING STANDARDS :

CCITT K20 :	10/700 μs	1.5kV
	5/310 μs	
VDE 0433 :	10/700 μs	2kV
	5/310 μs	
VDE 0878 :	1.2/50 μs	1.5kV
	1/20 μs	
I3124 :	0.5/700 μs	1.5kV
	0.2/310 μs	
FCC part 68 :	2/10 μs	2.5kV
BELLCORE		
TR-NWT-001089 :	2/10 μs	



FUNCTIONAL DIAGRAM



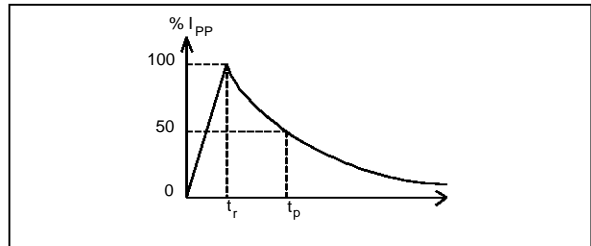
LCP1511D / LCP1512D

ABSOLUTE MAXIMUM RATINGS (-40°C ≤ T_{amb} ≤ 85°C)

Symbol	Parameter	Value	Unit
I _{PP}	Peak pulse current (see note 1)	10/1000μs 5/310μs 2/10μs	A
I _{TSM}	Non repetitive surge peak on-state current (F = 50Hz)	t _p = 10ms t _p = 1s	A
I _{GSM}	Maximum gate current (half sine wave -10ms)	2	A
V _{MLG} V _{MGL}	Maximum voltage LINE / GROUND Maximum voltage GATE / LINE	-100 -80	V
T _{stg} T _j	Storage temperature range Maximum junction temperature	- 55 to + 150 150	°C

Note 1 : Pulse waveform :

10/1000μs	t _r =10μs	t _p =1000μs
5/310μs	t _r =5μs	t _p =310μs
2/10μs	t _r =2μs	t _p =10μs



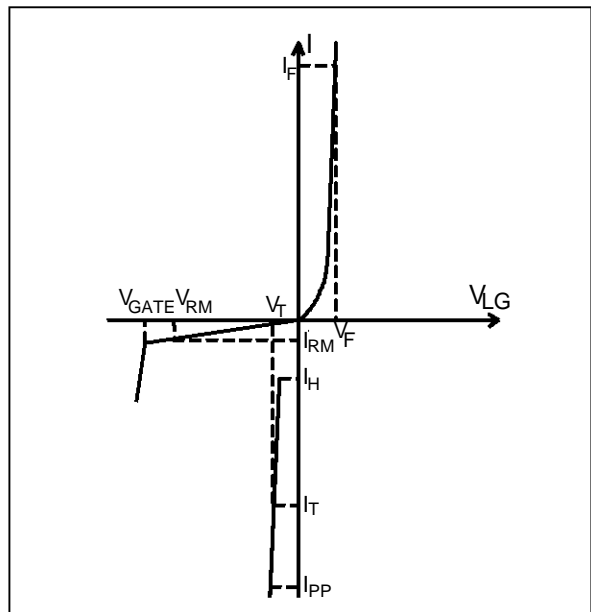
THERMAL RESISTANCE

Symbol	Parameter	Package	Value	Unit
R _{th (j-a)}	Junction to ambient	SO8 DIL8	170 125	°C/W °C/W

ELECTRICAL CHARACTERISTICS

(T_{amb} = 25°C, unless otherwise specified)

Symbol	Parameter
I _{GT}	Gate triggering current
I _H	Holding current
I _{RM}	Reverse leakage current LINE/GND
I _{RG}	Reverse leakage current GATE/LINE
V _{RM}	Reverse voltage LINE/GND
V _F	Forward voltage LINE/GND
V _{GT}	Gate triggering voltage
V _{FP}	Peak forward voltage LINE/GND
V _{DGL}	Dynamic switching voltage GATE/LINE
V _T	On-state voltage
V _{GATE}	GATE/GND voltage
V _{LG}	LINE/GND voltage
C _{off}	Off-state capacitance LINE/GND



PARAMETERS RELATED TO THE DIODE LINE/GND

Symbol	Test conditions	Maximum	Unit
V_F	Square pulse; $t_p=500\mu s$; $I_F=5A$	3	V
V_{FP} see note 1	10/700 μs 1.5kV $R_p=10\Omega$ 1.2/50 μs 1.5kV $R_p=10\Omega$ 2/10 μs 2.5kV $R_p=62\Omega$	5 7 12	V

Note 1 : See test circuit for V_{FP} ; R_p is the protection resistor located on the line card.

PARAMETERS RELATED TO THE PROTECTION THYRISTOR

Symbol	Test conditions	Min.	Max.	Unit
I_{GT}	$V_{GND/LINE} = -48V$	0.2	5	mA
I_H	$V_{GATE} = -48V$ (see note 2)	150		mA
V_{GT}	at I_{GT}		2.5	V
I_{RG}	$T_c=25^\circ C$ $V_{RG} = -75V$ $T_c=70^\circ C$ $V_{RG} = -75V$		5 50	μA
V_{DGL}	$V_{GATE} = -48V$ (see note 3) 10/700 μs 1.5kV $R_p=10\Omega$ $I_{PP}=30A$ 1.2/50 μs 1.5kV $R_p=10\Omega$ $I_{PP}=30A$ 2/10 μs 2.5kV $R_p=62\Omega$ $I_{PP}=38A$		10 20 25	V
V_T	Square pulse; $t_p=500\mu s$; $I_T=3A$		4	V

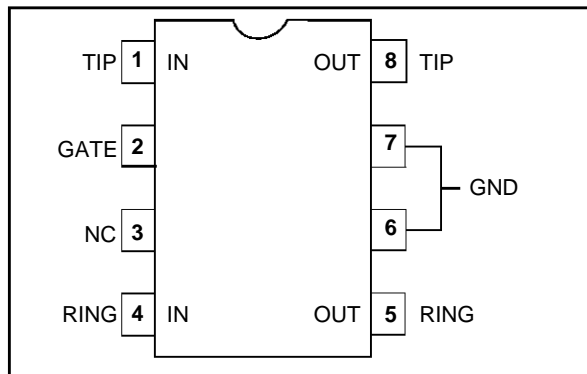
Note 2 : See the functional holding current (I_H) test circuit.

Note 3 : See test circuit for V_{DGL} .
The oscillations with a time duration less than 50ns are not taken into account.

PARAMETERS RELATED TO DIODE AND PROTECTION THYRISTOR

Symbol	Test conditions	Maximum	Unit
I_{RM}	$T_c=25^\circ C$ $V_{GATE/LINE} = -1V$ $V_{RM} = -75V$ $T_c=70^\circ C$ $V_{GATE/LINE} = -1V$ $V_{RM} = -75V$	5 50	μA
C_{off}	$V_R = -3V$ $F=1MHz$ $V_R = -48V$ $F=1MHz$	100 50	pF

APPLICATION NOTE



In order to take advantage of the "4 point" structure of the LCP, the TIP and RING lines have to cross through the device. In such case, the device will eliminate the overvoltages generated by the parasitic inductances of the wiring (Ldi/dt), especially for very fast transients.

LCP1511D / LCP1512D

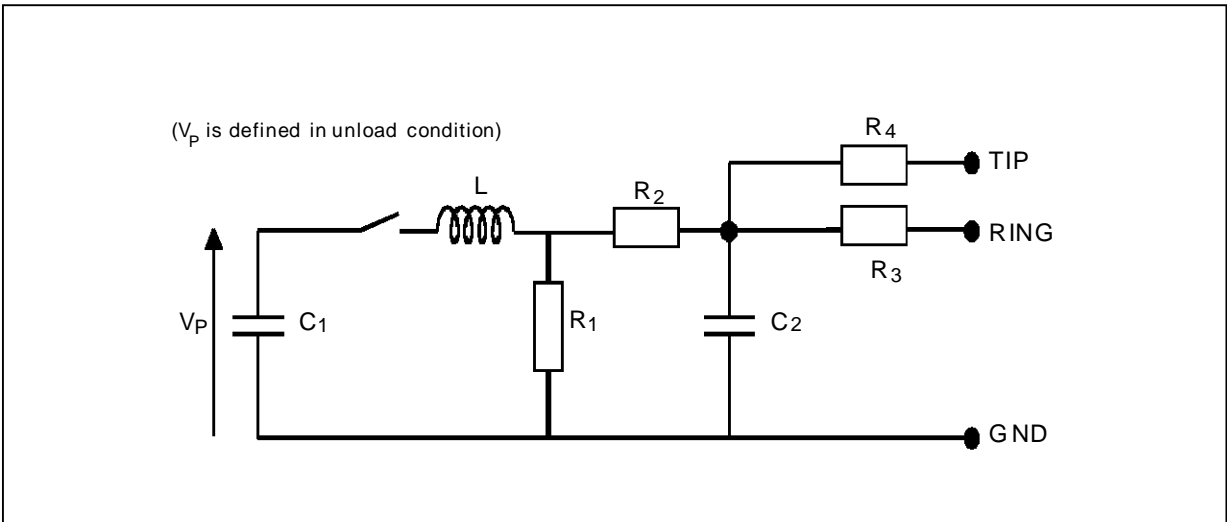
FUNCTIONAL HOLDING CURRENT (I_H) TEST CIRCUIT : GO-NO GO TEST

This is a GO-NO GO test which allows to confirm the holding current (I_H) level in a functional test circuit.

TEST PROCEDURE :

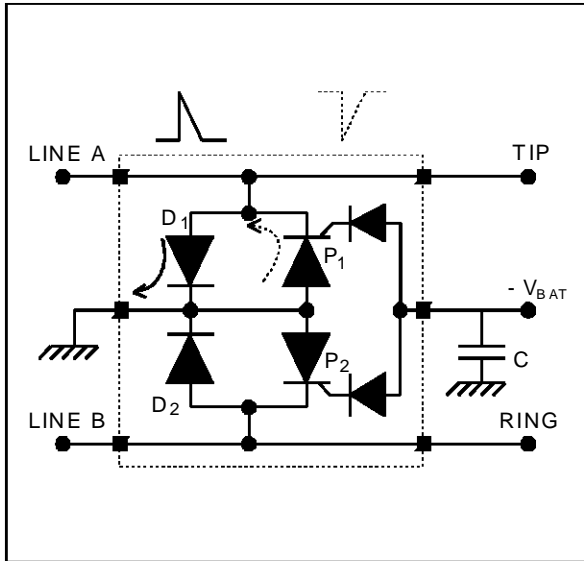
- Adjust the current level at the I_H value by short circuiting the D.U.T.
- Fire the D.U.T. with a surge current : $I_{PP} = 10A, 10/1000\mu s$.
- The D.U.T. will come back to the OFF-state within a duration of 50ms max.

TEST CIRCUIT FOR V_{FP} AND V_{DGL} PARAMETERS



Pulse (μs)		V_p (V)	C_1 (μF)	C_2 (nF)	L (μH)	R_1 (Ω)	R_2 (Ω)	R_3 (Ω)	R_4 (Ω)	I_{PP} (A)	R_p (Ω)
t_r	t_p										
10	700	1500	20	200	0	50	15	25	25	30	10
1.2	50	1500	1	33	0	76	13	25	25	30	10
2	10	2500	10	0	1.1	1.3	0	3	3	38	62

FUNCTIONAL DESCRIPTION



LINE A PROTECTION :

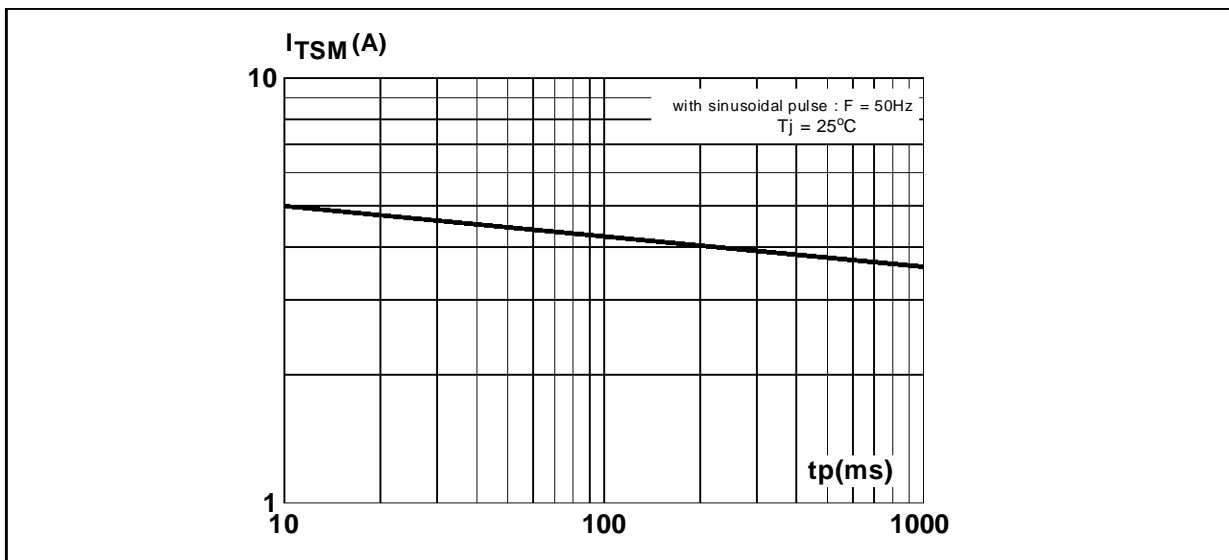
- For positive surges versus GND, the diode D1 will conduct.
- For negative surges versus GND, the protection device P1 will trigger at a voltage fixed by the $-V_{BAT}$ reference.

LINE B PROTECTION :

- For surges on line B, the operating mode is the same, D2 or P2 is activated.

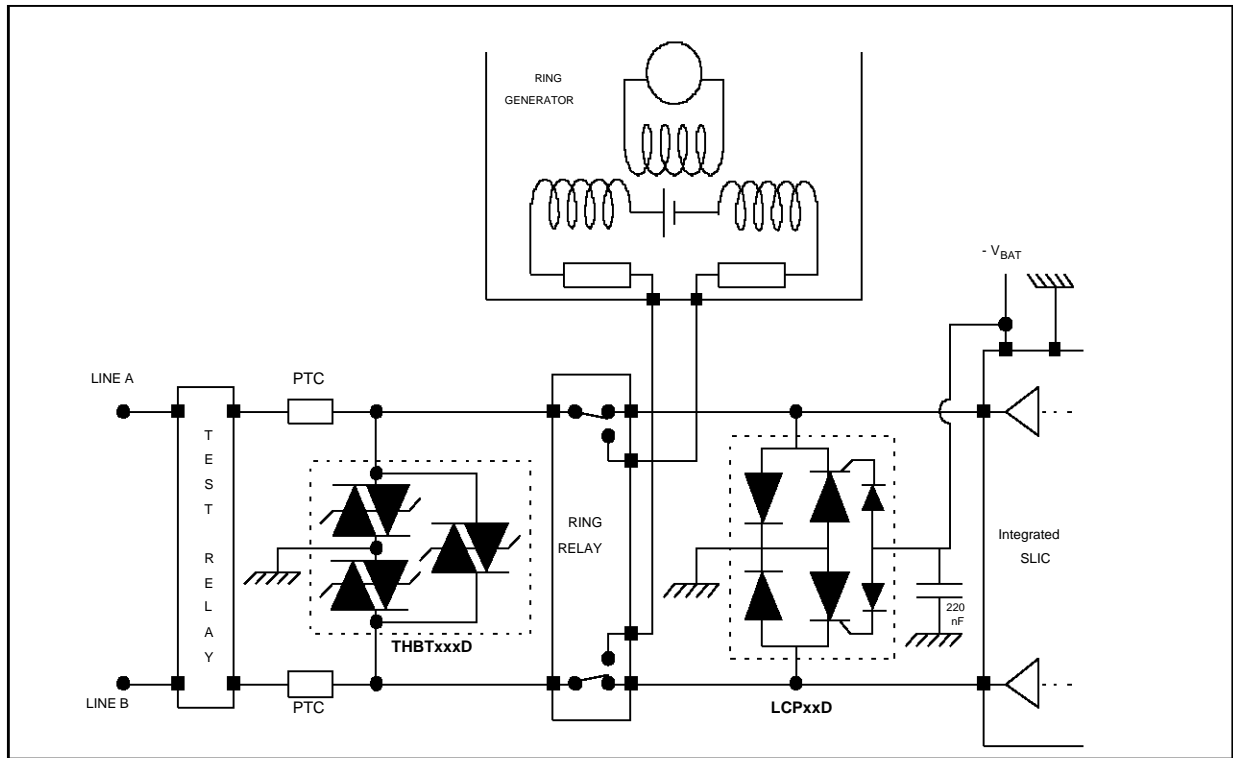
It is recommended to add a capacitor ($C=220nF$) close to the gate of the LCP, in order to speed up the triggering.

MAXIMUM NON REPETITIVE SURGE PEAK ON-STATE CURRENT



LCP1511D / LCP1512D

APPLICATION CIRCUIT : typical SLIC protection concept

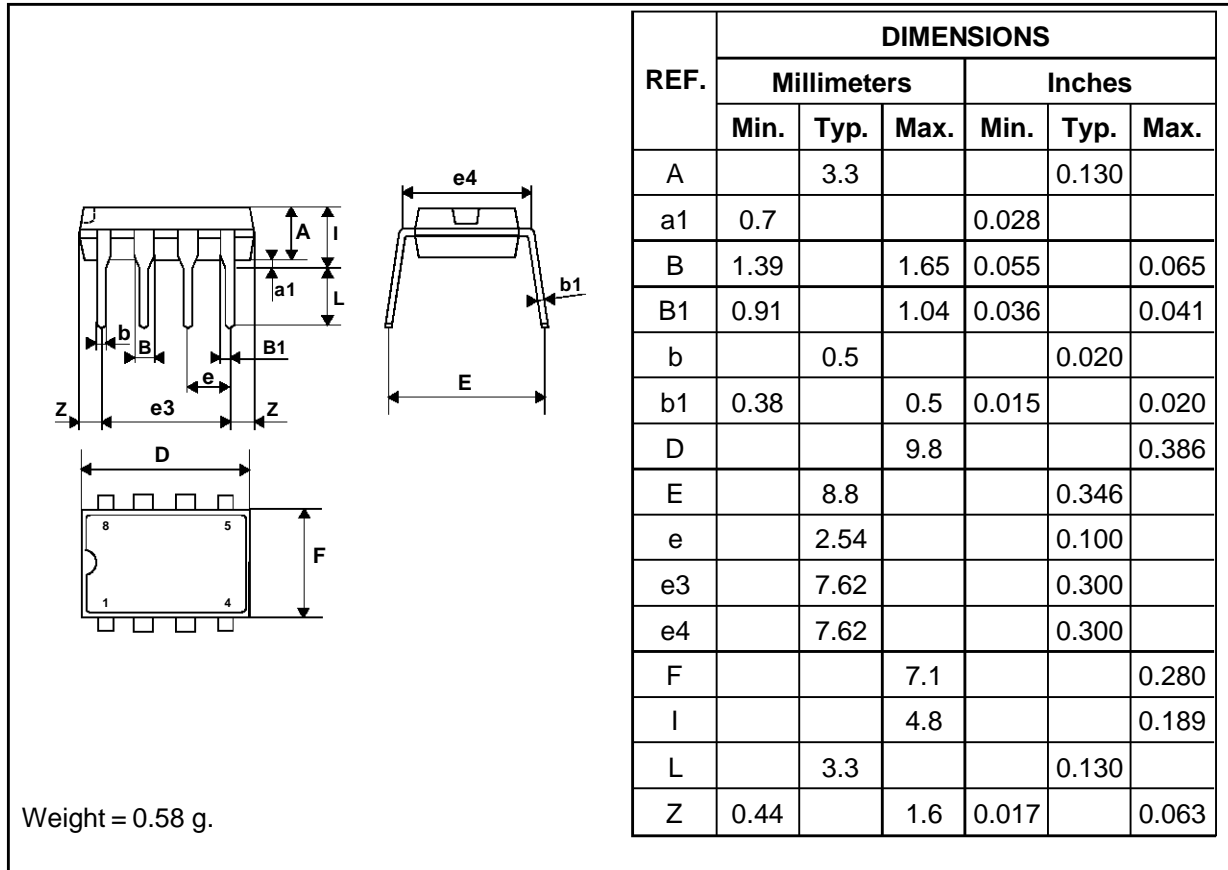


MARKING

Package	Type	Marking
SO8	LCP1511D	CP151D
DIL8	LCP1512D	CP152D

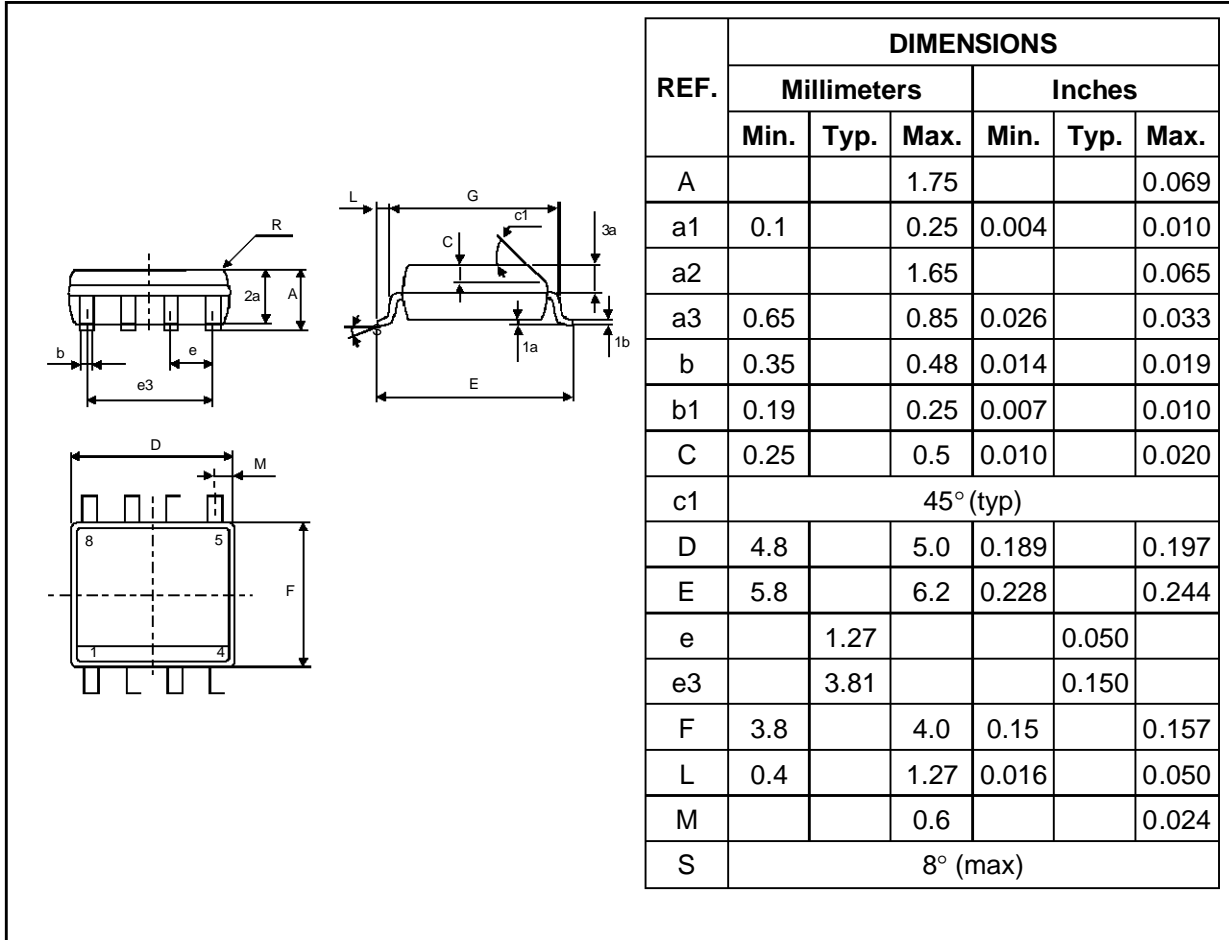
PACKAGE MECHANICAL DATA

DIL8 Plastic



LCP1511D / LCP1512D

PACKAGE MECHANICAL DATA SO8 Plastic



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